

Features

- High isolation 5000 VRMS
- Patented coplanar structure DMC-Isolator®
- Peak Breakdown Voltage
 - 250V CT3010-4L,CT3011-4L,CT3012-4L
 - 400V CT3020-4L,CT3021-4L,CT3022-4L,
 CT3023-4L
- Operating Temperature range 55 °C to 100 °C
- External Creepage ≥ 7.4mm
- Distance Through Isolation ≥ 0.4mm
- Clearance Distance ≥ 7.5mm (S/SL Type)
- Clearance Distance ≥ 8.0mm (M Type)
- RoHS and REACH Compliance
- Halogen Free Compliance (Optional)
- MSL class 1
- Regulatory Approvals
 - ✓ UL UL1577 (E364000)
 - ✓ VDE EN60747-5-5 (40039590)
 - ✓ CQC GB4943.1, GB8898 (14001104781)
 - ✓ IEC62368 (FI/41119)

Description

The CT3010-4L, CT3011-4L, CT3012-4L, CT3020-4L, CT3021-4L, CT3022-4L and CT3023-4L series consists of a Random Phase Photo Triac optically coupled to an Infrared-emitting diode in a 4-lead DIP package DMC-Isolator® with different lead forming options.

Applications

- Motor Controls
- Lamp ballasts
- Static AC Power Switch
- Solenoid/ Valve Control

Package Outline Schematic Anode 1 4 MT1 Cathode 2 3 MT2

Note: Different lead forming options available. See package dimension.



Absolute Maximum Ratings $T_A = 25^{\circ}C$, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameters | | Ratings | Units | Notes |
|-----------------------|---|-----------------------------------|------------|------------------|-------|
| Viso | Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.) | | 5000 | V _{RMS} | |
| Topr | Operating temperature | | -55 ~ +100 | °C | |
| Tstg | Storage temperature | | -55 ~ +150 | °C | |
| Tsol | Soldering temperature (F | or 10 seconds) | 260 | °C | |
| TJ | Junction temperature | | 115 | °C | |
| Emitter | | | | | |
| I _F | Forward current | | 60 | mA | |
| I _{F(TRANS)} | Peak transient current (≤1µs P.W,300pps) | | 1 | А | |
| V _R | Reverse voltage | | 6 | V | |
| P _D | Power dissipation | | 100 | mW | |
| Detector | • | | | • | |
| P _D | Power dissipation | | 300 | mW | |
| .,, | Off-State Output CT3010-4L,3011-4L,3012-4L | | 250 | V | |
| VDRM | Terminal Voltage | CT3020-4L,3021-4L,3022-4L,3023-4L | 400 | V | |
| I _{TM} | RMS on-state current | | 100 | mA | |
| I _{TSM} | Peak Repetitive Surge Current | | 1 | А | |

Electrical Characteristics $T_A = 25$ °C, unless otherwise specified

Emitter Characteristics

| Symbol | Parameters | Test Conditions | Min | Тур | Max | Units | Notes |
|-----------------|-------------------|----------------------|-----|-----|-----|-------|-------|
| VF | Forward voltage | I _F =10mA | - | - | 1.5 | V | |
| I _R | Reverse Current | V _R = 6V | - | - | 5 | μΑ | |
| C _{IN} | Input Capacitance | f= 1MHz | - | 45 | - | pF | |

Detector Characteristics

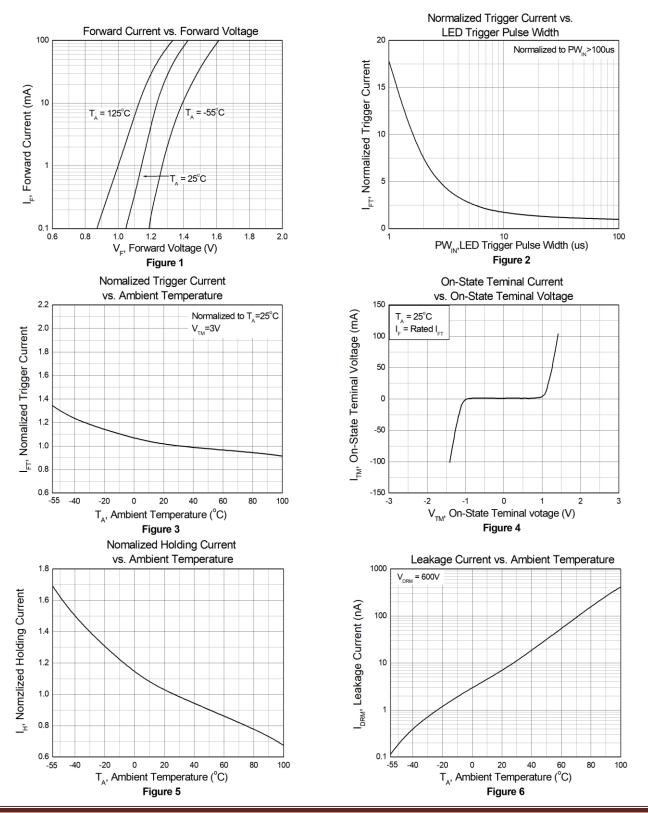
| Symbol | Parameters | Test Conditions | Min | Тур | Мах | Units | Notes |
|------------------|---|--|-----|-----|-----|-------|-------|
| I _{DRM} | Peak Blocking Current | I _F = 0mA, V _{DRM} = Rated V _{DRM} | - | - | 100 | nA | |
| V _{TM} | Peak On-State Voltage | I _F = Rated I _{FT} , I _{TM} = 100mA | - | - | 2.5 | V | |
| dv/dt | Critical Rate of Rise off-State Voltage | V _{PEAK} = Rated V _{DRM} | - | 100 | - | V/μs | |

Transfer Characteristics

| Symbol | Parameters | | Test Conditions | Min | Тур | Мах | Units | Notes |
|----------|---------------------------------------|----------------------|--|--------------------|------|-----|-------|-------|
| | | CT3020-4L | | - | - | 30 | | |
| | Input I _{FT} Trigger Current | C13010-4L, C13021-4L | Terminal Voltage = 3V I _{TM} =100mA | - | - | 15 | | |
| lfT | | CT3011-4L, CT3022-4L | | - | - | 10 | mA | |
| | | CT3012-4L, CT3023-4L | | - | - | 5 | | |
| | Holding Current | | Terminal Voltage from "ON" to | | | | | |
| lн | | | "OFF" | - | 250 | - | μΑ | |
| | | | "ON" state I _F =0mA | | | | | |
| R_{IO} | R _{IO} Isolation Resistance | | V _{IO} = 500V _{DC} , 40 ~ 60% R.H. | 1x10 ¹¹ | - | - | Ω | |
| Сю | Isolation Capacitance | | f= 1MHz | - | 0.25 | - | pF | |

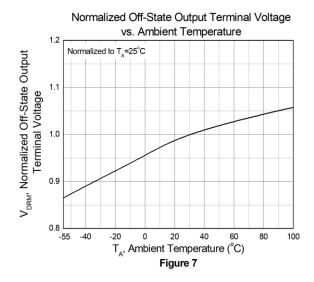


Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified

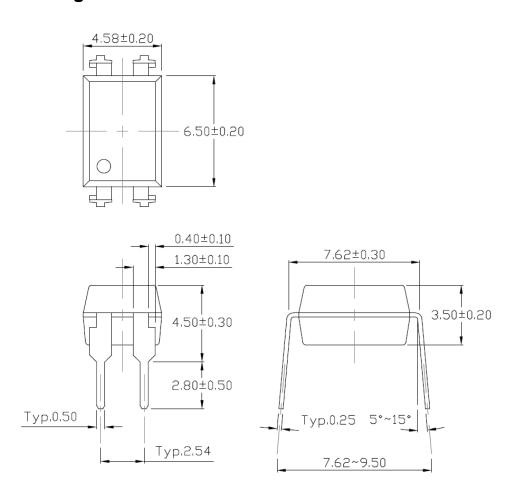




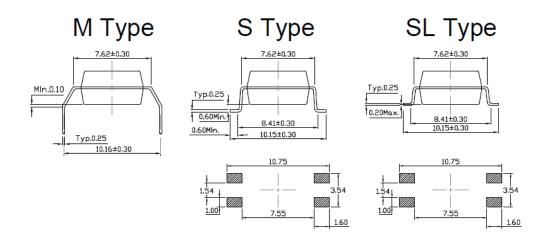
Typical Characteristic Curves $T_A = 25$ °C, unless otherwise specified



Package Dimension Dimensions in mm unless otherwise stated

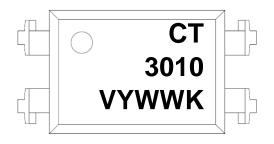


Forming Option Dimensions in mm unless otherwise stated





Marking Information



Note:

CT : Denotes "CT Micro"

3010 : Part Number

V : VDE Safety Mark Option (Blank or V)

Y : One Digit Year CodeWW : Two Digit Work WeekK : Manufacturing Code

Ordering Information

CT301X(V)(Y)(Z) -4L-G, CT302X(V)(Y)(Z) -4L-G

CT = Denotes "CT Micro"

301X = Part Numbers (Current Ration Option X=0, 1 or 2)

302X = Part Numbers (Current Ration Option X=0, 1, 2 or 3)

V = VDE Safety Mark Option (Blank or V)Y = Lead Form Option (S, SL, M or Blank)

Z = Tape and Reel Option (Blank, T1, T2, T3 or T4)

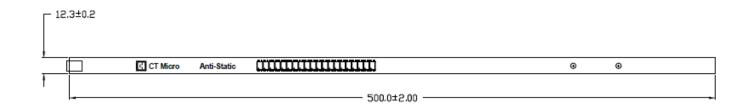
4L = 4-Lead DIP Package

G = Material Option (G: Halogen Free, Blank: Non-Halogen Free)

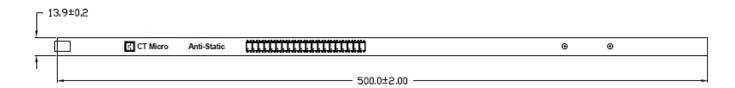
| Option | Option Description | |
|--------|---|-----------------|
| None | None Standard 4 Pin DIP | |
| M | Gullwing (400mil) Lead Forming | 100 Units/Tube |
| S(T1) | Surface Mount Lead Forming – With Option 1 Taping | 1500 Units/Reel |
| S(T2) | Surface Mount Lead Forming – With Option 2 Taping | 1500 Units/Reel |
| SL(T1) | Surface Mount (Low Profile) Lead Forming– With Option 1 Taping | 1500 Units/Reel |
| SL(T2) | Surface Mount (Low Profile) Lead Forming – With Option 2 Taping | 1500 Units/Reel |

Carrier Specifications Dimensions in mm unless otherwise stated

Tube Option Standard DIP

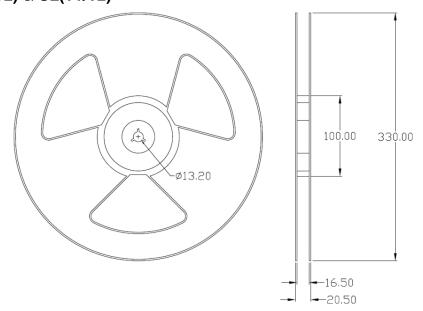


Tube Option M Type



Reel Dimension All dimensions are in mm, unless otherwise stated

Option S(T1/T2) & SL(T1/T2)

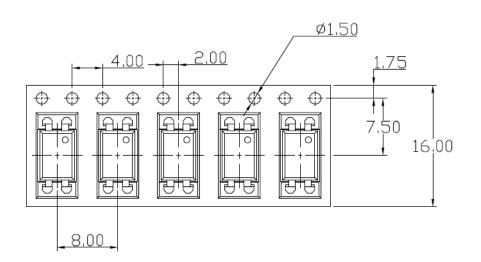


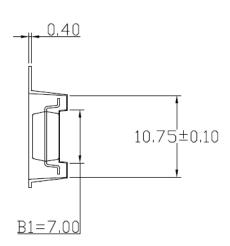


Carrier Tape Specifications Dimensions in mm unless otherwise stated

Option S(T1) & SL(T1)

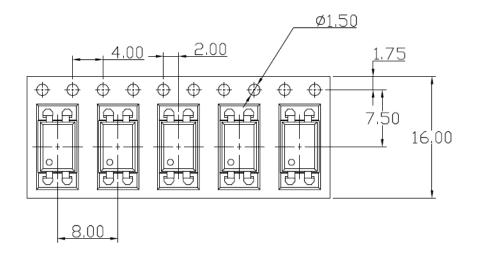
Input Direction

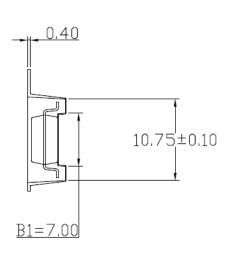




Option S(T2) & SL(T2)

Input Direction





Solderability spec (Follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

Wave soldering (Follow the JEDEC standard JESD22-A111)

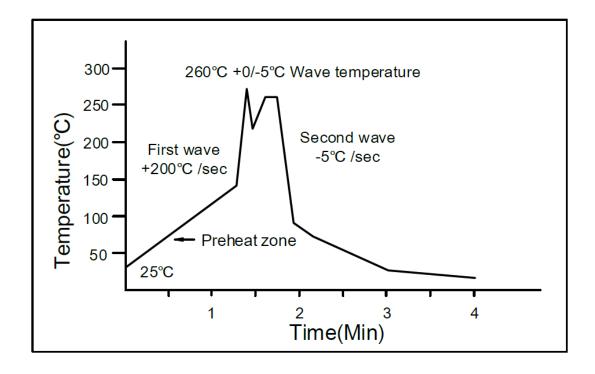
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature: 25 to 140°C.

Preheat time: 30 to 80 sec.



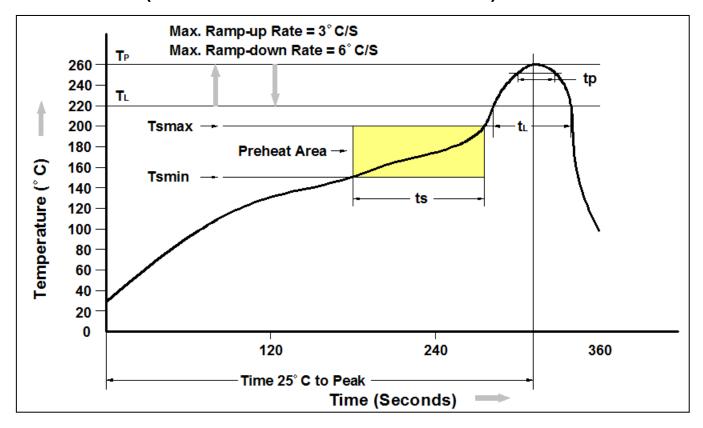
Iron soldering (Follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: 350±10°C

Time: 5 sec max.

Reflow Profile (Follow the JEDEC standard J-STD-020)



| Profile Feature | Pb-Free Assembly Profile |
|---|--------------------------|
| Temperature Min. (Tsmin) | 150°C |
| Temperature Max. (Tsmax) | 200°C |
| Time (ts) from (Tsmin to Tsmax) | 60-120 seconds |
| Ramp-up Rate (t∟ to t⊳) | 3°C/second max. |
| Liquidous Temperature (T _L) | 217°C |
| Time (t _L) Maintained Above (T _L) | 60 – 150 seconds |
| Peak Body Package Temperature | 260°C +0°C / -5°C |
| Time (t _P) within 5°C of 260°C | 30 seconds |
| Ramp-down Rate (T _P to T _L) | 6°C/second max |
| Time 25°C to Peak Temperature | 8 minutes max. |



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